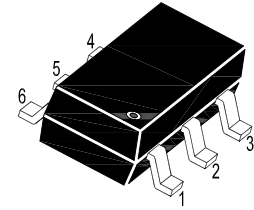
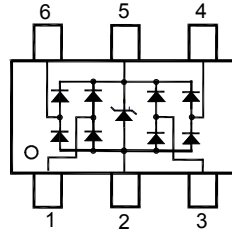


# ESDULC64DW

## 4-Channel Low Capacitance TVS Array



1. I/O1 2. GND 3. I/O2  
4. I/O3 5. V<sub>CC</sub> 6. I/O4  
Marking Code: **TF**  
SOT-363 Plastic package

### Absolute Maximum Ratings (T<sub>a</sub> = 25 °C)

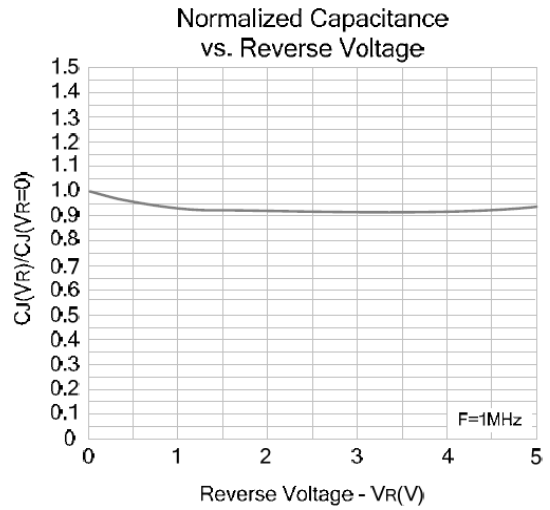
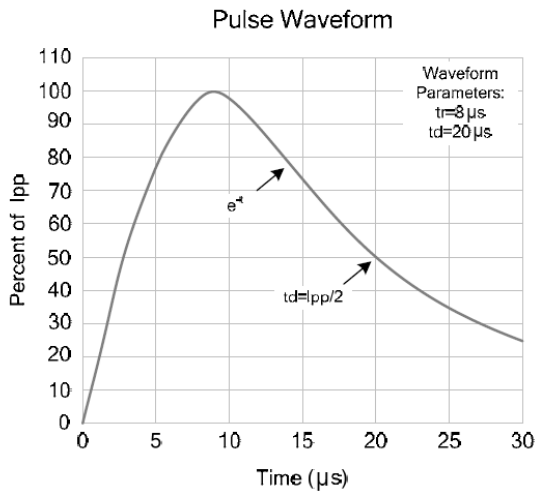
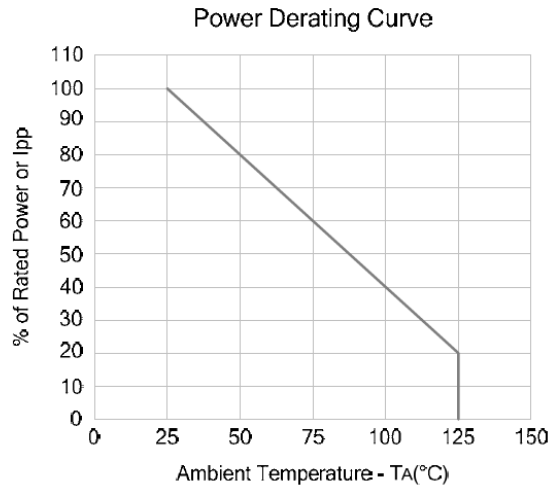
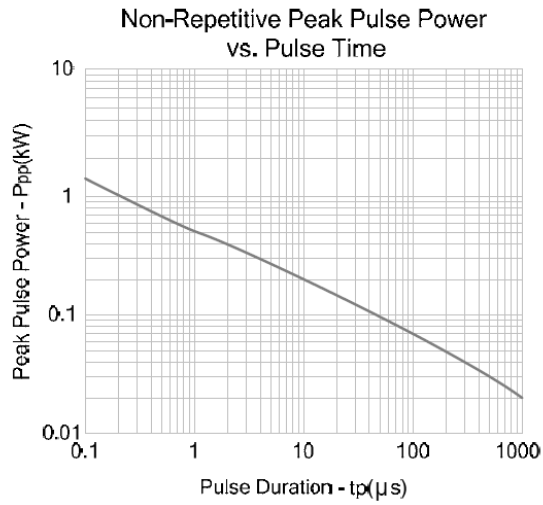
Parameter	Symbol	Value	Unit
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>PP</sub>	±15 ±15	KV
Maximum junction Temperature	T <sub>j</sub>	125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to + 150	°C

### Characteristics at T<sub>a</sub> = 25 °C

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at I <sub>R</sub> = 1 mA, Pin 5 to Pin 2	V <sub>BR</sub>	6	-	V
Leakaeg Current at V <sub>R</sub> = 5 V	I <sub>R</sub>	-	0.5	µA
Clamping Voltage at I <sub>PP</sub> = 1 A, tp = 8/20 µs, Any I/O Pin to Pin 2	V <sub>C</sub>	-	12	V
Clamping Voltage at I <sub>PP</sub> = 5 A, tp = 8/20 µs, Any I/O Pin to Pin 2	V <sub>C</sub>	-	17	V
Capacitance at V <sub>R</sub> = 0 V, f = 1 MHz, Between I/O Pin to Pin 2	C <sub>i/o-GND</sub>	-	1	pF
Capacitance at V <sub>R</sub> = 0 V, f = 1 MHz, Between I/O Pins	C <sub>i/o-i/o</sub>	-	0.5	pF

**TOP DYNAMIC**

# ESDULC64DW

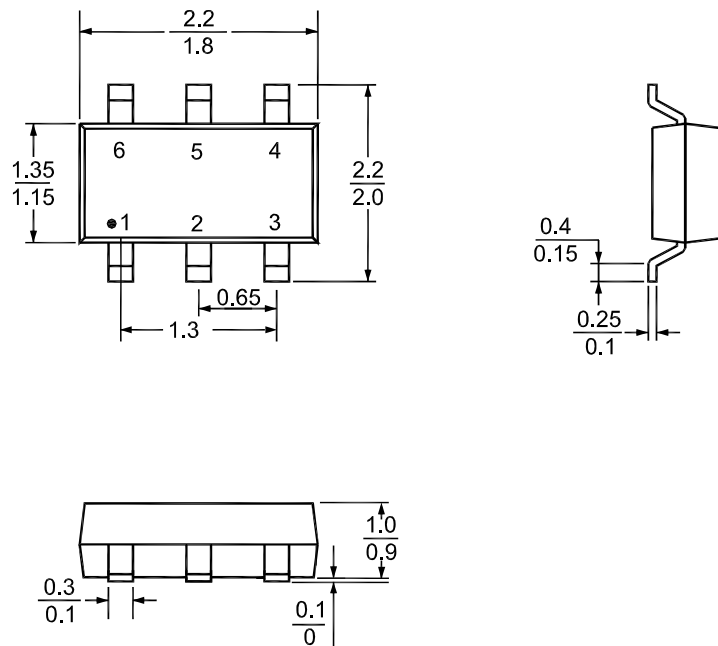


**TOP DYNAMIC**

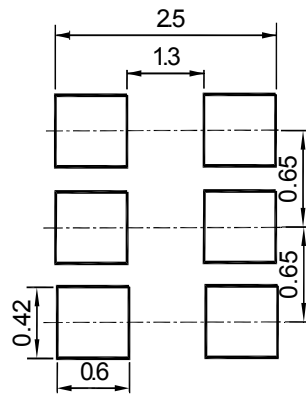
# ESDULC64DW

Package Outline Dimensions (Units: mm)

SOT-363



## Recommended Soldering Footprint



## Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-363	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

**TOP DYNAMIC**